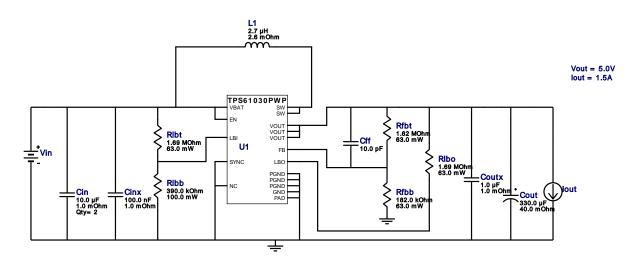
VinMin = 2.7V VinMax = 4.7V Vout = 5.0V Iout = 1.5A Device = TPS61030PWPR Topology = Boost Created = 2022-03-28 01:45:52.657 BOM Cost = \$2.47 BOM Count = 13 Total Pd = 0.67W

WEBENCH® Design Report

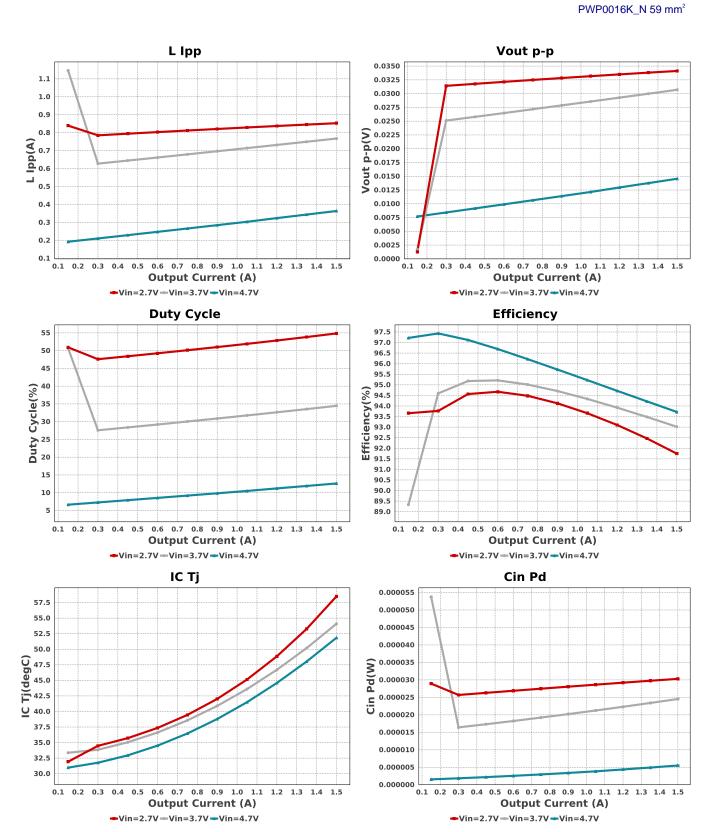
Design: 54 TPS61030PWPR TPS61030PWPR 2.7V-4.7V to 5.00V @ 1.5A

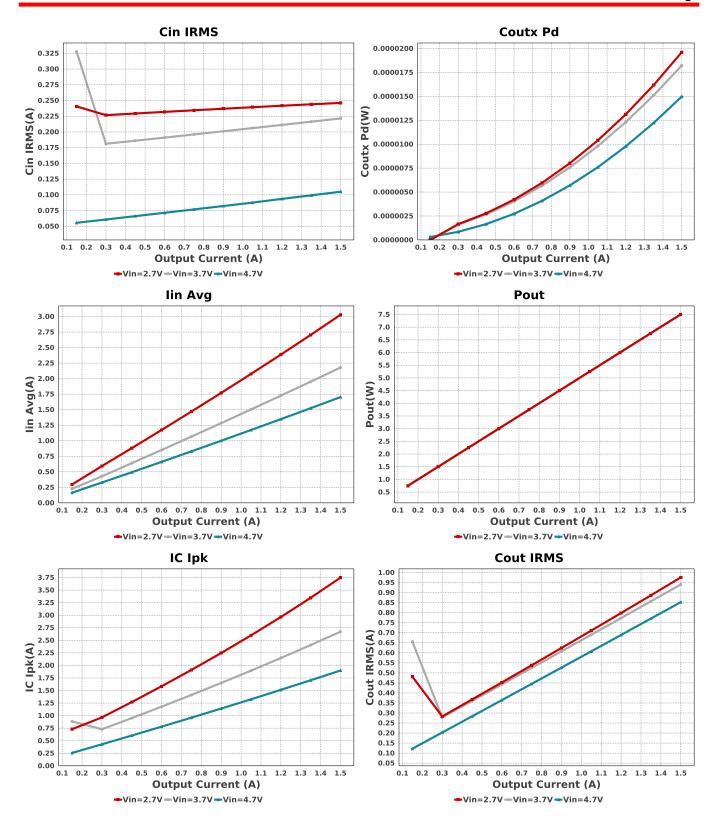


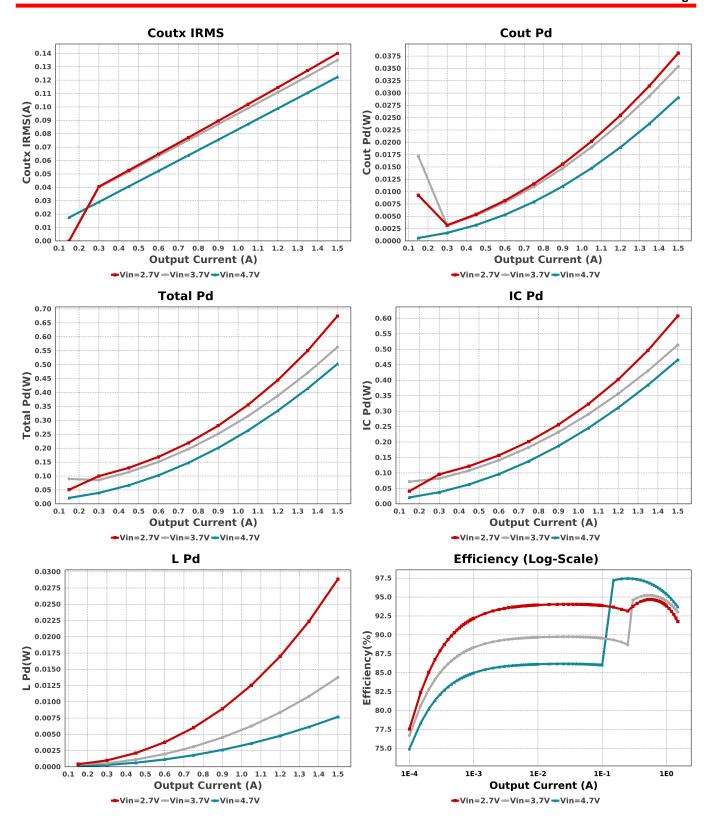
Electrical BOM

	<u>Manufacturer</u>	Part Number	Properties	Qty	Price	Footprint
Cff	Samsung Electro- Mechanics	CL02C100JO2ANNC Series= C0G/NP0	Cap= 10.0 pF VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	01005 2 mm ²
Cin	MuRata	GRJ155R60J106ME11D Series= X5R	Cap= 10.0 uF ESR= 1.0 mOhm VDC= 6.3 V IRMS= 0.0 A	2	\$0.02	0402_070 3 mm ²
Cinx	MuRata	GRM155R71A104KA01D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm ²
Cout	Panasonic	6TPC330MA Series= TPC	Cap= 330.0 uF ESR= 40.0 mOhm VDC= 6.3 V IRMS= 1.9 A	1	\$0.50	7343-20 59 mm ²
Coutx	Kemet	C0603C105K8PACTU Series= X5R	Cap= 1.0 uF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.01	0603 5 mm ²
L1	Coilcraft	SER1360-272KLB	L= 2.7 μH 2.6 mOhm	1	\$0.74	SER1360 225 mm ²
Rfbb	Vishay-Dale	CRCW0402182KFKED Series= CRCWe3	Res= 182.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rfbt	Vishay-Dale	CRCW04021M62FKED Series= CRCWe3	Res= 1.62 MOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rlbb	Yageo	RC0603FR-07390KL Series= ?	Res= 390.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm ²

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rlbo	Vishay-Dale	CRCW04021M69FKED Series= CRCWe3	Res= 1.69 MOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rlbt	Vishay-Dale	CRCW04021M69FKED Series= CRCWe3	Res= 1.69 MOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
U1	Texas Instruments	TPS61030PWPR	Switcher	1	\$1.11	







Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	246.158 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	30.297 μW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	975.732 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	38.082 mW	Capacitor	Output capacitor power dissipation
5.	Coutx IRMS	139.99 mA	Capacitor	Output capacitor_x RMS ripple current
6.	Coutx Pd	19.597 μW	Capacitor	Output capacitor_x power loss
7.	IC lpk	3.748 A	IC	Peak switch current in IC
8.	IC Pd	607.62 mW	IC	IC power dissipation
9.	IC Tj	58.497 degC	IC	IC junction temperature
10.	ICThetaJA	46.9 degC/W	IC	IC junction-to-ambient thermal resistance
11.	lin Avg	3.028 A	IC	Average input current

#	Name	Value	Category	Description
12.	L lpp	852.72 mA	Inductor	Peak-to-peak inductor ripple current
13.	L Pd	28.851 mW	Inductor	Inductor power dissipation
14.	Cin Pd	30.297 μW	Power	Input capacitor power dissipation
15.	Cout Pd	38.082 mW	Power	Output capacitor power dissipation
16.	Coutx Pd	19.597 μW	Power	Output capacitor_x power loss
17.	IC Pd	607.62 mW	Power	IC power dissipation
18.	L Pd	28.851 mW	Power	Inductor power dissipation
19.	Total Pd	674.643 mW	Power	Total Power Dissipation
20.	BOM Count	13	System Information	Total Design BOM count
21.	Duty Cycle	54.847 %	System Information	Duty cycle
22.	Efficiency	91.747 %	System Information	Steady state efficiency
23.	FootPrint	374.0 mm ²	System Information	Total Foot Print Area of BOM components
24.	Frequency	600.0 kHz	System Information	Switching frequency
25.	lout	1.5 A	System Information	lout operating point
26.	Mode	PWM CCM	System Information	PWM/PFM Mode
27.	Pout	7.5 W	System Information	Total output power
28.	Total BOM	\$2.47	System Information	Total BOM Cost
29.	Vin	2.7 V	System Information	Vin operating point
30.	Vout Actual	4.951 V	System Information	Vout Actual calculated based on selected voltage divider resistors
31.	Vout Tolerance	5.889 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
32.	Vout p-p	34.115 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

J			
Name	Value	Description	
lout	1.5	Maximum Output Current	
VinMax	4.7	Maximum input voltage	
VinMin	2.7	Minimum input voltage	
Vout	5.0	Output Voltage	
base_pn	TPS61030	Base Product Number	
source	DC	Input Source Type	
Та	30.0	Ambient temperature	

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

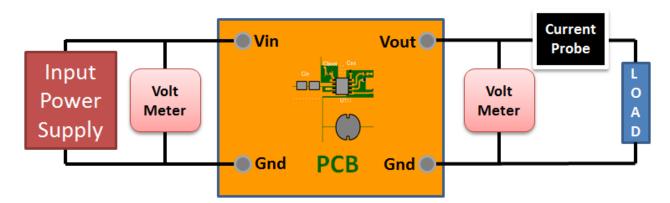
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 2.7V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

- 1. Master key: 235927DDE5FA19B1[v1]
- 2. TPS61030 Product Folder: http://www.ti.com/product/TPS61030: contains the data sheet and other resources.

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